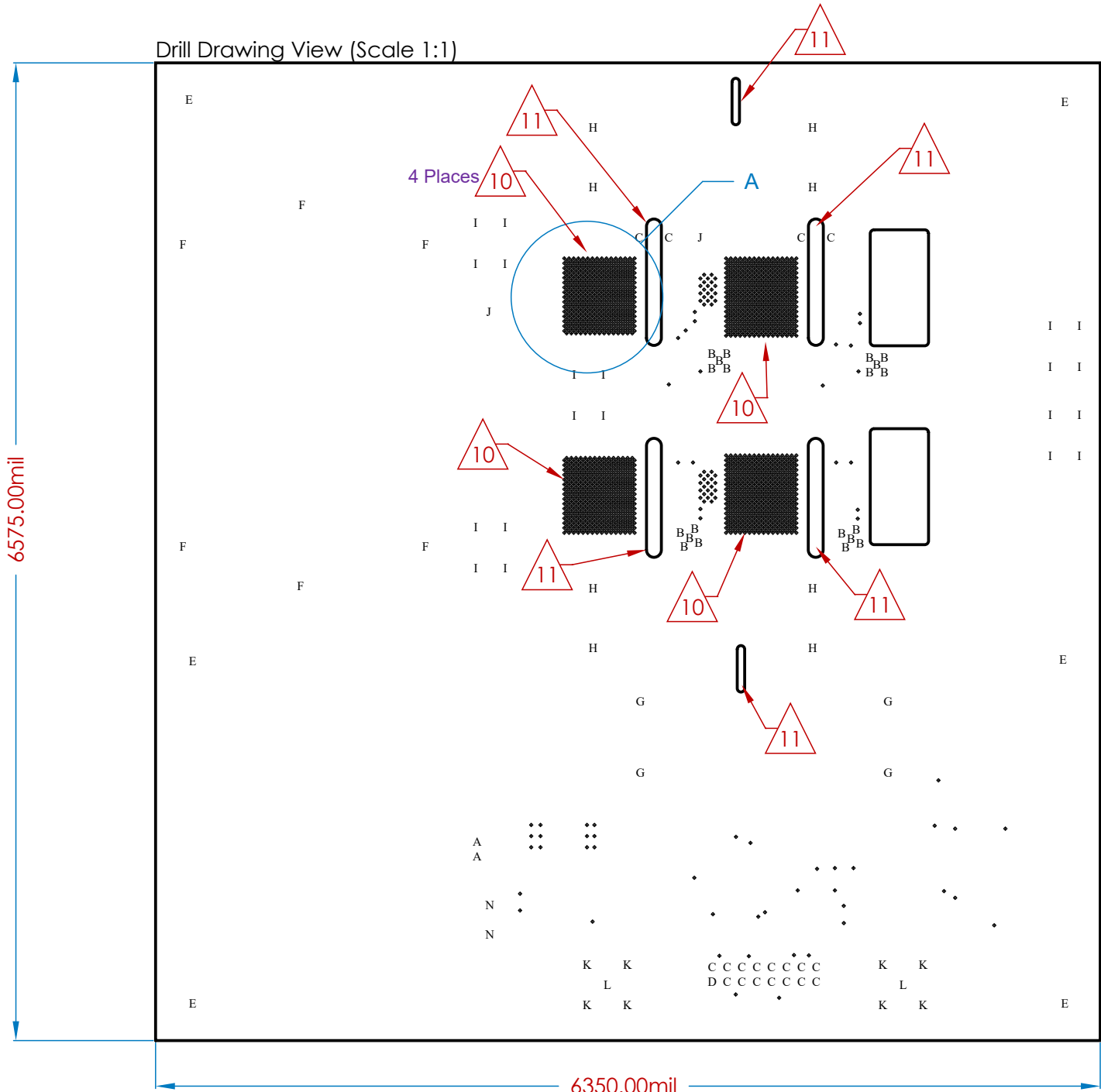
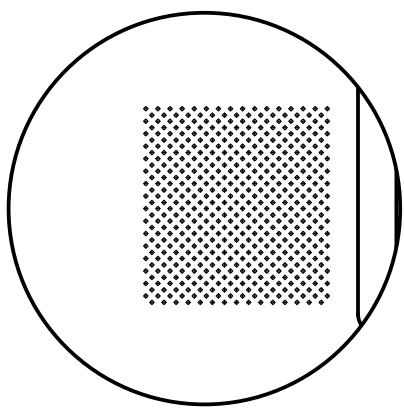


Drill Drawing View (Scale 1:1)





DETAIL A (Scale 2:1)
4 Places



Drill Table

Symbol	Count	Hole Size	Plated	Hole Type	Hole Length
A	2	40.16mil	Plated	Round	
B	20	33.07mil	Plated	Round	
C	19	40.00mil	Plated	Round	
D	1	45.00mil	Plated	Round	
E	6	156.00mil	Non-Plated	Round	
F	6	150.00mil	Non-Plated	Slot	500.00mil
G	4	175.00mil	Non-Plated	Round	
H	8	62.00mil	Plated	Round	
I	20	77.00mil	Plated	Round	
J	2	75.00mil	Plated	Round	
K	8	96.00mil	Plated	Round	
L	2	52.00mil	Plated	Round	
N	2	51.00mil	Plated	Round	
*	2121	12.00mil	Plated	Round	
2221 Total					

1. Fabricate per IPC 6012 Class II
2. Material: ISOLA FR406 or equivalent.
3. Total board thickness after plating: 0.063 +/- 10%
4. Final finish: ENIG
5. Soldermask both sides using photo-imagable process. Color: green
6. Silkscreen both sides using non-conductive ink. Color : white
7. All holes to be +/- 0.003 unless otherwise specified. Hole sizes are given after plating. Plated thru-hole shall have a min of 0.002 Cu internal plating.
8. Remove all burrs and sharp edges 0.015 min.
9. Surface finish: ENIG

-  Thermal vias in Deatils 'A' and 'B' are to be filled with SAN-EI PHP-900 Epoxy prior to plating. All other vias are tented.
-  Non-plated slots/cutouts

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.40mil	Solder Resist	Solder Mask	GTS
Copper	TOP	5.48mil		Signal	GTL
Core		15.00mil	FR-4	Dielectric	
Copper	INNER1	2.74mil		Signal	G1
Core		15.00mil	FR-4	Dielectric	
Copper	INNER2	2.74mil		Signal	G2
Core		15.00mil	FR-4	Dielectric	
Copper	BOTTOM	5.48mil		Signal	GBL
Surface Material	Bottom Solder	0.40mil	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 62.24mil					